Title (en)

MICROFLUIDIC CHIP

Title (de)

MIKROFLUIDISCHER CHIP

Title (fr)

PUCE MICROFLUIDIQUE

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Abstract (en)

The present invention relates to a microfluidic chip. The microfluidic chip comprises a chip main body and a liquid sac storage piece; a liquid inlet is provided on the chip main body; the liquid sac storage piece is disposed on the chip main body, and a liquid sac cavity used for placing a liquid sac is disposed on the liquid sac storage piece; the liquid sac cavity is provided with a liquid outlet, the liquid outlet communicating with the liquid inlet; and a piercing piece is disposed in the liquid sac cavity; when the liquid sac is placed in the liquid sac cavity, there is a space between the liquid sac and the piercing piece; when the pressing force exerted on the liquid sac exceeds a preset value, the piecing piece can pierce the liquid sac. The described microfluidic chip can reduce the rejection rate of the chip, and improve the test repeatability and stability of the chip.

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